



PATENT

2827

Case Docket No. MICRON.110A

Date: January 23, 2003

Page 1

In re application of : Jiang
App. No. : 09/471,071
Filed : December 21, 1999
For : DIE ATTACH MATERIAL
FOR TBGA OR FLEXIBLE
CIRCUITRY
Examiner : Alcala, J.
Art Unit : 2827

I hereby certify that this correspondence and all marked
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2327, Arlington, VA 22202, on

January 23, 2003

(Date)

Lang J. McHardy, Reg. No. 50,591

UNITED STATES PATENT AND TRADEMARK OFFICE
BOX NON-FEE AMENDMENT
P.O. Box 2327
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	20	—	20	= 0 ×	\$18	= \$0
Independent Claims	5	—	7	= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add					\$280	= \$0
Time Extension Fee						\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$0

(X) Five sheets of replacement drawings.

(X) Return prepaid postcard.

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PATENT

Case Docket No. MICRON.110A

Date: January 23, 2003

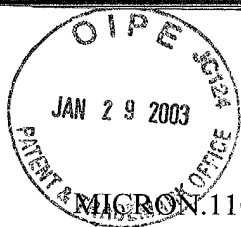
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- (X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.
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012203



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Tongbi Jiang) Group Art Unit 2827
Appl. No. : 09/471,071)
Filed : December 21, 1999)
For : DIE ATTACH MATERIAL)
FOR TBGA OR FLEXIBLE)
CIRCUITRY)
Examiner : Jose Alcala)

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AMENDMENT

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action dated October 23, 2002, please amend the above-identified application as indicated below.

IN THE CLAIMS:

Please amend the claims as follows:

8. An integrated circuit package, comprising:
a die;
a die attach layer over the die; and
an array of solder balls over the die attach layer;
wherein the die attach layer has a coefficient of thermal expansion of less than
about 106 ppm/°C.